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REMARKS

Claims 1-2 are pending in this application. The Examiner has rejected claims 1-2 under 35 USC 103(a) as being unpatentable over Guyer et al. (US 6,583,989) in view of Snyder et al. (US 4,318,489).

In response, claims 1 and 2 have been amended without changing the subject matters thereof. For at least the following reasons, Applicant respectfully traverses Examiner's rejections.

Applicant's invention is focusing on the bottom board of a computer casing to provide better structural support on the location of CPU and much and much heavier heat dissipating device of a computer system. Accordingly, a dent portion (a hollow space 132 described in the spec. and shown in the Figures) occupied a small part of the bottom board 13 (page 4, lines 20-22) is formed by depressing a portion of the bottom board downwardly. Therefore, the CPU 21 and the heat dissipating device 23 are positioned above the dent portion 132 and the heat dissipating device mounted on the CPU can be fixed to the mother board by plural pillars 133 disposed in the dent portion 132.

In comparison, Guyer merely discloses a computer system, like other conventional cnes, including a casing, a mother board, a CPU and a heat dissipating device. However, there is no any disclosure of Guyer to teach or suggest forming a dent portion on a bottom board of the computer casing so that Guyer, of course, does not disclose CPU and heat dissipating device to be located above the dent portion of the bottom board. Although Snyder's plastic bottle discloses the center of the bottom of the bottle may be depressed inwardly into the bottle to increase the clearance between the bottom and a surface on AMENDMENT

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which the bottle stands, the skilled person in the computer field still may not and will not combine Guyer with Snyder to obtain Applicant's amended claims 1 and 2. First of all, Applicant respectfully disagrees Examiner's assertion that Guyer and Snyder are analogous art. According to Guyer and Snyder's International or US classification or their searching field, no one class between them is the same. As such, it seems to Applicant that the skilled person in the computer field can not combine Guyer with Snyder to teach Applicant's invention. Moreover, Guyer's bottom board does not have the dent portion and Guyer's CPU and heat dissipating device do not need to locate at a specific position corresponding to a structural strength stronger than any other part of the bottom board. Snyder merely discloses the plastic bottle but nothing about the support providing by the inwardly depressed center of the bottom. Therefore, there is no linkage or lacking of connection between Guyer and Snyder to have the skilled person in the computer field combining them together to showing obviousness with respect to Applicant's invention.

On the other hand, even Guyer can combine with Snyder to teach Applicant's invention. Snyder discloses the center of the bottom is depressed inwardly into the bottle to increase the clearance between the bottom and the surface on which the bottle stands, which is still distinct from Applicant's limitations of claim 1 to have the dent portion depressed outwardly from the internal space to provide the structural strength stronger than any other part of the bottom board. In addition, neither Guyer nor Snyder discloses to place the CPU and the heat dissipating devoice above the dent portion. Therefore, Applicant respectfully submits that it would not be obvious to the skilled person in the computer field to combine Guyer with Snyder to obtain Applicant's claim 1.

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Applicant further respectfully disagrees Examiner's assertion to reject Applicant's claim 2. Although the skilled person in the computer field can have a plurality of fixing elements used to fix the heat dissipating device to the mother board by passing through the mother board to screw in corresponding pillars, there is no disclosure and not obvious to dispose the pillars in the dent portion of the bottom board of the computer casing as in Applicant's claim 2. Moreover, Applicant would like to indicate that there is no such description in Applicant's invention to make fixing elements to reduce heat. Therefore, Applicant respectfully submits that it would not be obvious to the skilled person in the computer field to combine Guyer with Snyder to obtain Applicant's claim 2.

In view of the foregoing, the application is believed to be in condition for allowance. Entry of the amendments and issuance of a Notice of Allowance is therefore respectfully requested. If any additional fee is required, please charge Deposit Account Number 502751.

Respectfully submitted,

You Hung Chen